Huawei Ascend 910B

Da Vinci v2 | OAM | 2024 | SMIC 7nm

OVERVIEW

—	64 GB	1.6 TB/s	400 W
FP32 TFLOPS	VRAM HBM2e	Memory Bandwidth	TDP

PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	800.0	8	Standard
FP16	400.0	16	Standard
BF16	400.0	16	Standard

MEMORY SPECIFICATIONS

Capacity	64 GB
Type	HBM2e
Bandwidth	1.6 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	400 W
Est. Max Power	460 W
FP32 Efficiency	—
FP16 Efficiency	1.00 TFLOPS/W

HARDWARE DETAILS

Vendor: Huawei

Architecture: Da Vinci v2

Process Node: SMIC 7nm

Form Factor: OAM

Launch Year: 2024

INTERCONNECT

GPU-to-GPU: HCCS

Bandwidth: 392 GB/s